MC10H136

Universal Hexadecimal Counter

Description

The MC10H136 is a high speed synchronous hexadecimal counter. This 10H part is a functional/pinout duplication of the standard MECL 10K™ family part, with 100% improvement in counting frequency and no increase in power-supply current.

Features

- Counting Frequency, 250 MHz Minimum
- Power Dissipation, 625 mW Typical
- Improved Noise Margin 150 mV
  (Over Operating Voltage and Temperature Range)
- Voltage Compensated
- MECL 10K Compatible
- These Devices are Pb-Free, Halogen Free and are RoHS Compliant

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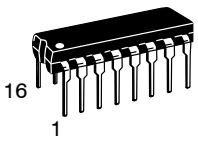
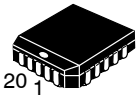
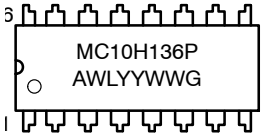


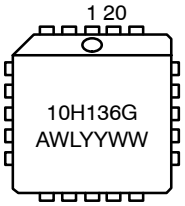
PDIP−16
P SUFFIX
CASE 648−08



PLLC−20
FN SUFFIX
CASE 775−02

MARKING DIAGRAMS*





A	= Assembly Location
WL	= Wafer Lot
YY	= Year
WW	= Work Week
G	= Pb-Free Package

*For additional marking information, refer to Application Note AND8002/D.

ORDERING INFORMATION

Device	Package	Shipping†
MC10H136FNG	PLCC−28 (Pb-Free)	46 Units/Tube
MC10H136PG	PDIP−16 (Pb-Free)	25 Units/Tube

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

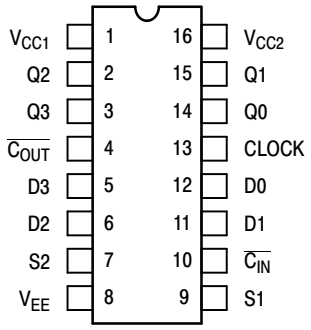
Table 1. FUNCTION SELECT TABLE

$\overline{CIN}$	S1	S2	Operating Mode
X	L	L	Preset (Program)
L	L	H	Increment (Count Up)
H	L	H	Hold Count
L	H	L	Decrement (Count Down)
H	H	L	Hold Count
X	H	H	Hold (Stop Count)

Table 2. SEQUENTIAL TRUTH TABLE*

INPUTS								OUTPUTS				
S1	S2	D0	D1	D2	D3	$\overline{\text{Carry In}}$	Clock **	Q0	Q1	Q2	Q3	$\overline{\text{Carry Out}}$
L	L	L	L	H	H	X	H	L	L	H	H	L
L	H	X	X	X	X	L	H	H	L	H	H	H
L	H	X	X	X	X	L	H	L	H	H	H	H
L	H	X	X	X	X	L	H	H	H	H	H	L
L	H	X	X	X	X	H	L	H	H	H	H	H
L	H	X	X	X	X	H	H	H	H	H	H	H
H	H	X	X	X	X	X	H	H	H	H	H	H
L	L	H	H	L	L	X	H	H	H	H	L	L
H	L	X	X	X	X	L	H	L	H	L	L	H
H	L	X	X	X	X	L	H	H	L	L	L	H
H	L	X	X	X	X	L	H	L	L	L	L	L
H	L	X	X	X	X	L	H	H	L	H	L	H

* Truth table shows logic states assuming inputs vary in sequence shown from top to bottom.
** A clock H is defined as a clock input transition from a low to a high logic level.



Pin assignment is for Dual-in-Line Package.

Figure 1. Pin Assignment

Table 3. MAXIMUM RATINGS

Symbol	Characteristic	Rating	Unit
V_{EE}	Power Supply (V_{CC} = 0)	−8.0 to 0	Vdc
V_I	Input Voltage (V_{CC} = 0)	0 to V_{EE}	Vdc
I_{out}	Output Current Continuous Surge	 50 100	mA
T_A	Operating Temperature Range	0 to +75	°C
T_{stg}	Storage Temperature Range Plastic Ceramic	 −55 to +150 −55 to +165	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Table 4. ELECTRICAL CHARACTERISTICS (V_{EE} = −5.2 V ±5%) (Note 1)

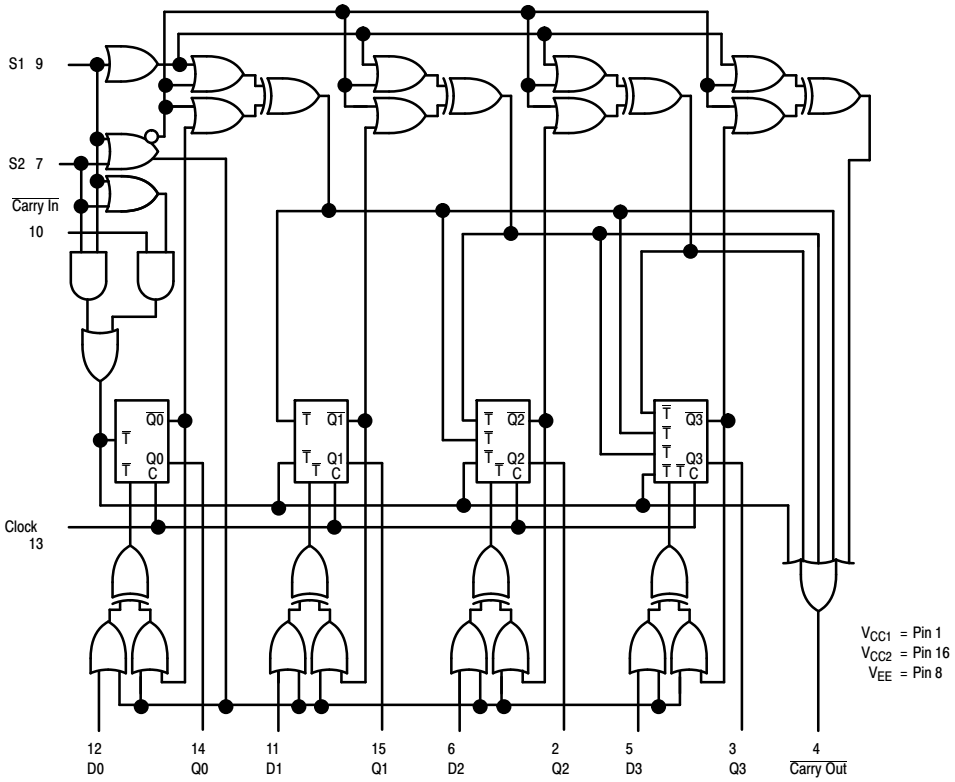
		0°		25°		75°		
Symbol	Characteristic	Min	Max	Min	Max	Min	Max	Unit
I_E	Power Supply Current	–	165	–	150	–	165	mA
I_{inH}	Input Current High Pins 5, 6, 11, 12, 13 Pin 9 Pin 7 Pin 10	 – – – –	 430 670 535 380	 – – – –	 275 420 335 240	 – – – –	 275 420 335 240	μA
I_{inL}	Input Current Low	0.5	–	0.5	–	0.3	–	μA
V_{OH}	High Output Voltage	−1.02	−0.84	−0.98	−0.81	−0.92	−0.735	Vdc
V_{OL}	Low Output Voltage	−1.95	−1.63	−1.95	−1.63	−1.95	−1.60	Vdc
V_{IH}	High Input Voltage	−1.17	−0.84	−1.13	−0.81	−1.07	−0.735	Vdc
V_{IL}	Low Input Voltage	−1.95	−1.48	−1.95	−1.48	−1.95	−1.45	Vdc

1. Each MECL 10H™ series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 lfpm is maintained. Outputs are terminated through a 50 Ω resistor to −2.0 V.

Table 5. AC CHARACTERISTICS

Symbol	Characteristic	0°		25°		75°		Unit
		Min	Max	Min	Max	Min	Max	
t_{pd}	Propagation Delay							ns
	Clock to Q	0.7	2.3	0.7	2.4	0.7	2.5	
	Clock to Carry Out	1.0	4.8	1.0	4.9	1.0	5.0	
	Carry in to Carry Out	0.7	2.5	0.7	2.6	0.7	2.7	
t_{set}	Set-up Time							ns
	Data (D0 to C)	2.0	–	2.0	–	2.0	–	
	Select (S to C)	3.5	–	3.5	–	3.5	–	
	Carry In (C_{in} to C)	2.0	–	2.0	–	2.0	–	
	(C to C_{in})	0	–	0	–	0	–	
t_{hold}	Hold Time							ns
	Data (C to D0)	0	–	0	–	0	–	
	Select (C to S)	−0.5	–	−0.5	–	−0.5	–	
	Carry In (C to C_{in})	0	–	0	–	0	–	
	(C_{in} to C)	2.2	–	2.2	–	2.2	–	
f_{count}	Counting Frequency	250	–	250	–	250	–	MHz
t_r	Rise Time	0.5	2.3	0.5	2.4	0.5	2.5	ns
t_f	Fall Time	0.5	2.3	0.5	2.4	0.5	2.5	ns

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.



NOTE: FLIP-FLOPS WILL TOGGLE WHEN ALL $\overline{T}$ INPUTS ARE LOW.

Figure 2. Logic Diagram

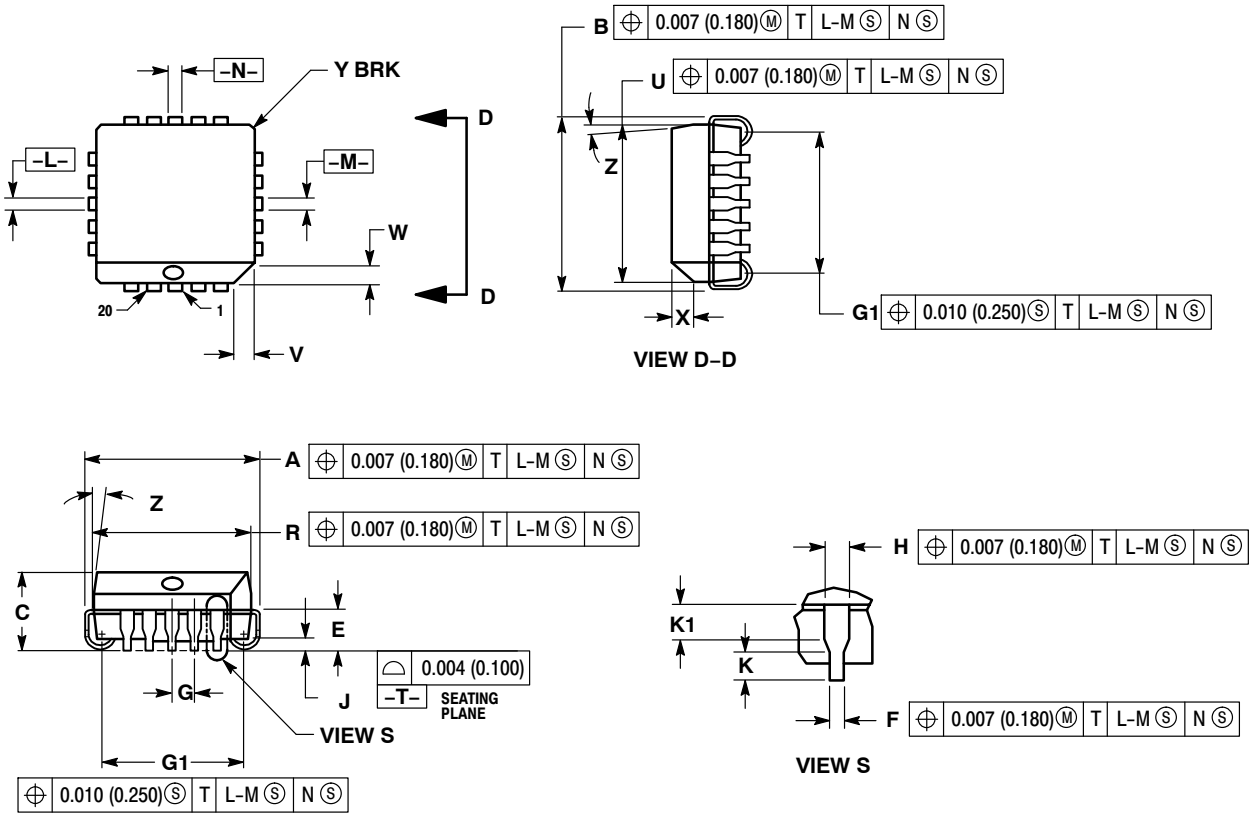
APPLICATION INFORMATION

The MC10H136 is a high speed synchronous counter that operates at 250 MHz. Counter operating modes include count up, count down, pre-set and hold count. This device allows the designer to use one basic counter for many applications.

The S1, S2, control lines determine the operating modes of the counter. In the pre-set mode, a clock pulse is necessary to load the counter with the information present on the data inputs (D0, D1, D2, and D3). Carry out goes low on the terminal count or when the counter is being pre-set.

PACKAGE DIMENSIONS

20 LEAD PLLC
CASE 775−02
ISSUE F

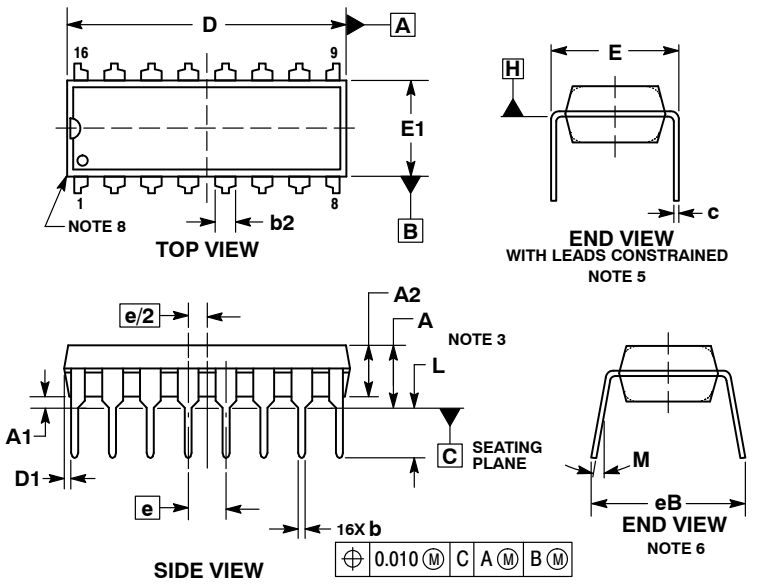


NOTES:
1. DIMENSIONS AND TOLERANCING PER ANSI Y14.5M, 1982.
2. DIMENSIONS IN INCHES.
3. DATUMS –L–, –M–, AND –N– DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.
4. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM –T–, SEATING PLANE.
5. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
6. DIMENSIONS IN THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
7. DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.385	0.395	9.78	10.03
B	0.385	0.395	9.78	10.03
C	0.165	0.180	4.20	4.57
E	0.090	0.110	2.29	2.79
F	0.013	0.021	0.33	0.53
G	0.050 BSC		1.27 BSC	
H	0.026	0.032	0.66	0.81
J	0.020	---	0.51	---
K	0.025	---	0.64	---
R	0.350	0.356	8.89	9.04
U	0.350	0.356	8.89	9.04
V	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Y	---	0.020	---	0.50
Z	2 °	10 °	2 °	10 °
G1	0.310	0.330	7.88	8.38
K1	0.040	---	1.02	---

PACKAGE DIMENSIONS

PDIP−16
CASE 648−08
ISSUE V



NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: INCHES.
3. DIMENSIONS A, A1 AND L ARE MEASURED WITH THE PACKAGE SEATED IN JEDEC SEATING PLANE GAUGE GS−3.
4. DIMENSIONS D, D1 AND E1 DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS ARE NOT TO EXCEED 0.10 INCH.
5. DIMENSION E IS MEASURED AT A POINT 0.015 BELOW DATUM PLANE H WITH THE LEADS CONSTRAINED PERPENDICULAR TO DATUM C.
6. DIMENSION eB IS MEASURED AT THE LEAD TIPS WITH THE LEADS UNCONSTRAINED.
7. DATUM PLANE H IS COINCIDENT WITH THE BOTTOM OF THE LEADS, WHERE THE LEADS EXIT THE BODY.
8. PACKAGE CONTOUR IS OPTIONAL (ROUNDED OR SQUARE CORNERS).

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	----	0.210	---	5.33
A1	0.015	----	0.38	---
A2	0.115	0.195	2.92	4.95
b	0.014	0.022	0.35	0.56
b2	0.060 TYP		1.52 TYP	
C	0.008	0.014	0.20	0.36
D	0.735	0.775	18.67	19.69
D1	0.005	----	0.13	---
E	0.300	0.325	7.62	8.26
E1	0.240	0.280	6.10	7.11
e	0.100 BSC		2.54 BSC	
eB	----	0.430	---	10.92
L	0.115	0.150	2.92	3.81
M	----	10°	---	10°

STYLE 1:
PIN 1. CATHODE
2. CATHODE
3. CATHODE
4. CATHODE
5. CATHODE
6. CATHODE
7. CATHODE
8. CATHODE
9. ANODE
10. ANODE
11. ANODE
12. ANODE
13. ANODE
14. ANODE
15. ANODE
16. ANODE

STYLE 2:
PIN 1. COMMON DRAIN
2. COMMON DRAIN
3. COMMON DRAIN
4. COMMON DRAIN
5. COMMON DRAIN
6. COMMON DRAIN
7. COMMON DRAIN
8. COMMON DRAIN
9. GATE
10. SOURCE
11. GATE
12. SOURCE
13. GATE
14. SOURCE
15. GATE
16. SOURCE

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